



## Micro/Nano-Scale Heat Transfer

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### Message from the Guest Editors

Dear Colleagues,

The fast-paced progress in micromachining technology enables the fabrication of micron-sized mechanical devices. The miniaturization and increased functionality of modern devices induce an appreciable hike in the operating temperature, motivating research on microscale heat transfer to improve thermal management in confined space. Microscale heat transfer, in view of its efficiency and robustness in the thermal regulation of microscale cooling devices, micro-electromechanical systems, energy conversion devices, and other MEMS and biomedical applications, is of great value. Microscale cooling devices such as microchannel heat sinks, micro heat pipes and micro heat exchangers are increasingly important in current and future heat removal applications. The incorporation of nanostructured materials such as nanoparticles, nanofluids and nanostructured surfaces into the micro-scale devices are important for the performance enhancement. The objective of this Special Issue is to present recent findings in micro/nano-scale heat transfer, with an emphasis on the basic understanding of the heat transfer processes and their applications to practical problems.





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